



1/27/97  
2/1/97  
15  
/327,887

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : KIM

Examiner: T. BILODEAU

Serial No.: 08/327,887

Group Art Unit: 1107

**RECEIVED**

Filed : October 24, 1994

Docket: 9983.3-US-01 **JAN 30 1997**

Title : METHOD FOR FILLING CONTACT HOLES WITH METAL BY  
TWO-STEP DEPOSITION

**GROUP 110**

**January 2, 1997**

AMENDMENT UNDER 37 C.F.R. §1.111

Hon. Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

In response to the outstanding Office Action mailed November 8, 1996, please amend the above identified patent application as follows:

In the Claims

Please amend claims 1 and 9 as follows:

1. (Amended) A method for filling contact holes with metal by two-step deposition of metal layers, said method comprising the steps of:

providing a silicon substrate;

15